

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-37 (canceled).

Claim 38 (previously presented): The device transfer method as set forth in claim 52, wherein the plurality of first devices and the plurality of second devices are held in the embedded state in different areas on the first substrate.

Claim 39 (cancelled).

Claim 40 (previously presented): The method of manufacturing a display apparatus as set forth in claim 53, wherein display is carried out through simple matrix driving by impressing a voltage on the devices through the first electric wirings and the second electric wirings.

Claim 41 (cancelled).

Claim 42 (previously presented): The method of manufacturing a display apparatus as set forth in claim 54, wherein the first devices and the second devices have different characteristics.

Claim 43 (previously presented): The method of manufacturing a display apparatus as set forth in claim 54, wherein the plurality of first devices and the plurality of second devices are held in the embedded state in different areas on the second substrate.

Claim 44 (previously presented): The method of manufacturing a display apparatus as set forth in claim 54, wherein display is carried out through simple matrix driving by impressing

a voltage on the plurality of first devices or the plurality of second devices through the first electric wirings and the second electric wirings.

Claim 45 (previously presented): The method of manufacturing a display apparatus as set forth in claim 54, wherein any one of the plurality of first devices and the plurality of second devices are any one of display devices and driving circuit devices.

Claim 46 (previously presented): The method of manufacturing a display apparatus as set forth in claim 45, wherein display is carried out through active matrix driving by impressing a voltage on the display devices by the driving circuit devices.

Claim 47 (cancelled).

Claim 48 (previously presented): The device transfer method as set forth in claim 54, wherein a tack of the pressure sensitive adhesive layer provided on the second substrate is greater than a tack of the temporary adhesion layer provided on the first substrate.

Claim 49 (previously presented): The device transfer method as set forth in claim 48, wherein the tack of at least one of the pressure sensitive adhesive layer and the temporary adhesion layer is changed so that the tack of the pressure sensitive adhesive layer will be greater than the tack of the temporary adhesion layer.

Claim 50 (previously presented): The device transfer method as set forth in claim 52, further comprising curing the pressure sensitive adhesive layer using a heating treatment.

Claim 51 (cancelled).

Claim 52 (previously presented): A device transfer method comprising:

(a) arranging a plurality of devices on a temporary adhesion layer of a temporary holding substrate;

(b) embedding the plurality of devices into a plurality of positions of an entirely uncured pressure sensitive adhesive layer provided on a transfer substrate by positioning the transfer substrate and the temporary adhesion substrate in close proximity thereof such that the temporary adhesion layer comes into contact with the pressure sensitive adhesive layer, and the plurality of devices become entirely embedded within the pressure sensitive adhesive layer so that the plurality of devices are substantially flush with the surface of the pressure sensitive adhesive layer,

(c) repeating (a) and (b) at least once with a different plurality of devices, wherein for each subsequent embedding step:

(i) the entire pressure sensitive adhesive layer remains in an uncured state,
and

(ii) the different plurality of devices are embedded into different positions of the same pressure sensitive adhesive layer.

Claim 53 (previously presented): A method of manufacturing a display apparatus comprising:

(a) arranging a plurality of devices on a temporary adhesion layer of a temporary holding substrate;

(b) embedding the plurality of devices into a plurality of positions of an entirely uncured pressure sensitive adhesive layer provided on a transfer substrate by positioning the transfer substrate and the temporary adhesion substrate in close proximity thereof such that the temporary adhesion layer comes into contact with the pressure sensitive adhesive layer, and the plurality of devices become entirely embedded within the pressure sensitive adhesive layer so that the plurality of devices are substantially flush with the surface of the pressure sensitive adhesive layer, and the devices are light emitting diodes,

(c) stripping the devices from the temporary holding substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding the devices in an embedded and uncured state within the pressure sensitive adhesive layer,

(d) repeating (a) to (c) at least once with a different plurality of devices, wherein for each subsequent embedding and stripping step:

- (i) the entire pressure sensitive adhesive layer remains in an uncured state, and
- (ii) the different plurality of devices are embedded into different positions of the same pressure sensitive adhesive layer;
- (c) hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer;
- (f) forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto a side on which the first electric wirings are formed of the pressure sensitive adhesive layer, and stripping the transfer substrate and the pressure sensitive adhesive layer from each other; and
- (g) providing the pressure sensitive adhesive layer with openings reaching the devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 54 (currently amended): A method of manufacturing a display apparatus comprising:

- (a) forming a first temporary adhesion layer on a surface of a first substrate, and arranging a plurality of first devices on the first temporary adhesion layer;
- (b) embedding the plurality of first devices into a pressure sensitive adhesive layer provided on a second substrate by positioning the first and second substrates in close proximity thereof such that the temporary adhesion layer comes into contact with the pressure sensitive adhesive layer and the plurality of first devices are entirely embedded within the pressure sensitive adhesive layer such that the plurality of second devices become substantially flush with the surface of the pressure sensitive adhesive layer, the entire pressure sensitive adhesive layer being in an uncured state;
- (c) stripping the plurality of first devices from the first substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding the plurality of first devices in an embedded and uncured state within the pressure sensitive adhesive layer;
- (d) forming a second temporary adhesion layer on a surface of a third substrate, and arranging a plurality of second devices on the second temporary adhesion layer;

(e) further embedding the plurality of second devices arranged on the third substrate into the pressure sensitive adhesive layer by positioning the third and second substrates in close proximity thereof such that the plurality of second devices arranged on the third substrate penetrate the surface of the pressure sensitive adhesive layer;

(f) stripping the plurality of second devices from the third substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding the plurality of second devices in an embedded and uncured state within the pressure sensitive adhesive layer, where the plurality of first devices are embedded in the pressure sensitive adhesive layer;

(g) hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer where the plurality of first devices and the plurality of second devices are held in an embedded and cured state within the pressure sensitive adhesive layer;

(h) forming first electric wirings on the pressure sensitive adhesive layer, adhering a ~~third-fourth~~ substrate onto the side on which the first electric wirings are formed of the pressure sensitive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

(i) providing the pressure sensitive adhesive layer with openings reaching the plurality of first devices or the plurality of second devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer, wherein the first devices and second devices are light emitting diodes.